Silicon N-Channel MOS FET

HITACHI

Application

Low frequency power amplifier

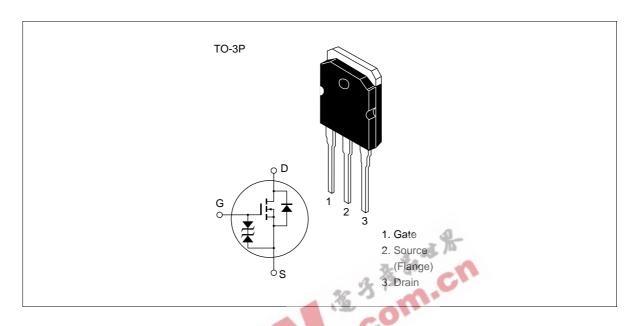
· Com.cn Complementary pair with 2SJ160, 2SJ161 and 2SJ162

Features

- Good frequency characteristic
- High speed switching
- Wide area of safe operation
- Enhancement-mode
- Good complementary characteristics
- Equipped with gate protection diodes
- Suitable for audio power amplifier



Outline



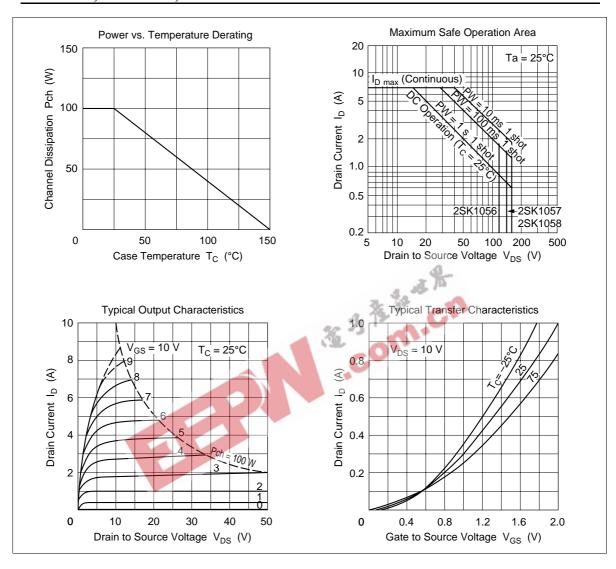
Absolute Maximum Ratings (Ta = 25°C)

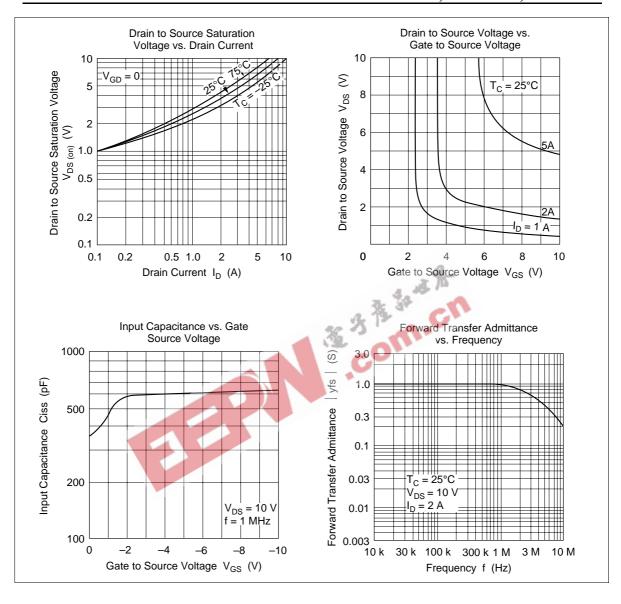
Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1056	V _{DSX}	120	V
	2SK1057		140	
	2SK1058		160	
Gate to source voltage		$V_{\sf GSS}$	±15	V
Drain current	I _D	7	А	
Body to drain diode reverse d	I _{DR}	7	A	
Channel dissipation	Pch*1	100	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

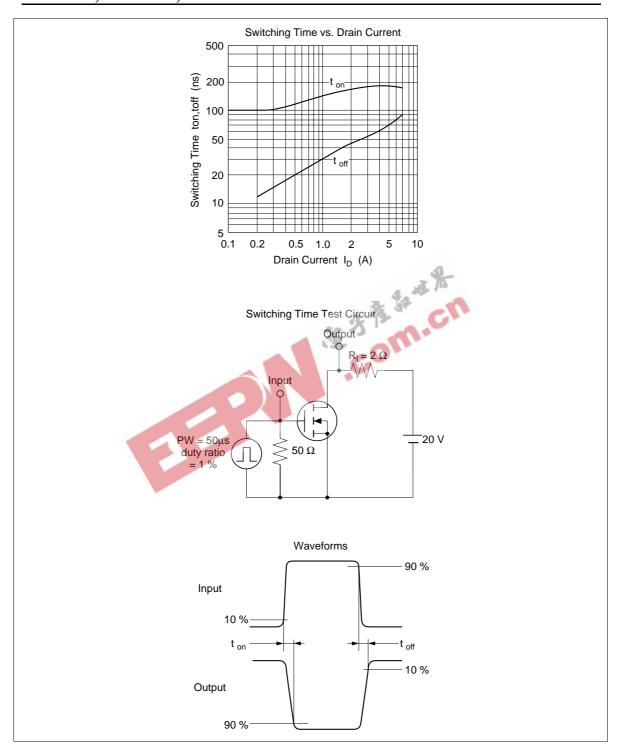
Note: 1. Value at $T_c = 25^{\circ}C$

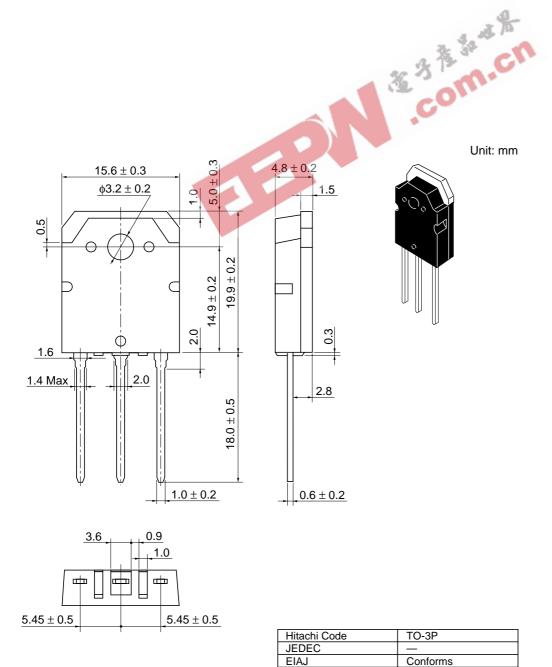
Electrical Characteristics (Ta = 25°C)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1056	$V_{(BR)DSX}$	120	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = -10 \text{ V}$
breakdown voltage	2SK1057	_	140	_			
	2SK1058	_	160	_			
Gate to source break voltage	kdown	$V_{(BR)GSS}$	±15	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source cutof	f voltage	$V_{\rm GS(off)}$	0.15	_	1.45	V	$I_D = 100 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain to source satu voltage	ration	$V_{DS(sat)}$	_	_	12	V	$I_D = 7 \text{ A}, V_{GD} = 0 *1$
Forward transfer adr	mittance	yfs	0.7	1.0	1.4	S	$I_D = 3 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	600	_	pF	$V_{GS} = -5 \text{ V}, V_{DS} = 10 \text{ V},$
Output capacitance		Coss	_	350	_	pF	f = 1 MHz
Reverse transfer cap	pacitance	Crss	_	10	- 3k	pF	-10
Turn-on time		\mathbf{t}_{on}	_	180	为下	ns	$V_{DD} = 20 \text{ V}, I_D = 4 \text{ A},$
Turn-off time		\mathbf{t}_{off}	- ,	60		ns	
Note: 1. Pulse tes	et .			1	,00		









EIAJ

Weight (reference value)

5.0 g

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